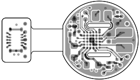
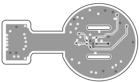
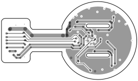


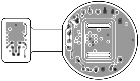
TOP/L1|4 LAYERS



L2|4 LAYERS



L3|4 LAYERS



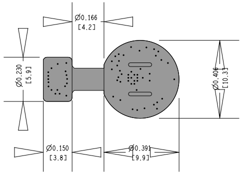
BOTTOM/L4|4 LAYERS

FAB NOTES:

1. THE PWB SHALL BE FABRICATED TO IPC-6012,CLASS 2.
   AND WORKMANSHIP SHALL CONFORM TO IPC-A-600,CLASS 2. CURRENT REVISIONS.
2. BOARD MATERIAL SHALL BE 150 Tg/350 Td OR EQUIVALENT. RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-410B. COLOR:NATURAL.
3. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPOVED AND MARKED ON THE FINISHED BOARD.
4. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE 0.001 INCH.
   WITH A MINIMUM ANNULAR RING OF .002 INCH.
5. OVERALL BOARD THICKNESS TO BE 15.6+/-4 mil. AND APPLIES AFTER ALL LAMINATION AND PLATING AND PATING PROCESSES, MEASURED FROM SOLDERMASK TO SOLDERMASK
6. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

PROCESS NOTES:

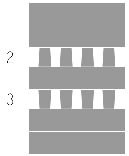
1. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC),
   COLOR: MATTE BLACK. SOLDERMASK SHALL CONFIRM TO IPC-SM-840. CLASS H. CURRENT REV.
2. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK.
   COLOR: WHITE.



FAB01_DRILL1-4

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
•	4.0	+3.0/-3.0	PLATED	65

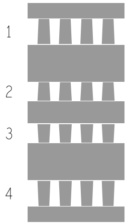
STACKUP



	POLYIMIDE_FILM_1MIL	1.000 MILS
	ADHESIVE_EPOXY	1.000 MILS
2	COPPER	0.700 MILS
	POLYIMIDE_FILM_1MIL	1.000 MILS
3	COPPER	0.700 MILS
	ADHESIVE_EPOXY	1.000 MILS
	POLYIMIDE_FILM_1MIL	1.000 MILS

FLEX_L2-L3: 6.400 MILS

STACKUP



	SOLDERMASK	0.500 MILS
1	COPPER	1.400 MILS
	FR-4	4.700 MILS
2	COPPER	0.700 MILS
	POLYIMIDE_FILM_1MIL	1.000 MILS
3	COPPER	0.700 MILS
	FR-4	4.700 MILS
4	COPPER	1.400 MILS
	SOLDER_MASK	0.500 MILS

RIGID_FLEX_L1-L4: 15.600 MILS